

DESCRIPTION

DMI-7005 is a high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications. The resin is supplied pre-dissolved in anisole (methoxy benzene) for ease of incorporation. The unique **DMI-7005** joins the nature of a thermoplastic resin (flexibility, high strength) and a thermoset resin (curability, hydrophobicity, ease of customer use) together with superior electrical properties for the next generation of high frequency applications.

TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	CONDITIONS	RESULT
Appearance at Room Temperature	Visual	Amber Liquid
Resin content	Gravimetric	25%
Viscosity @ 25°C	Cone & Plate @ 5 RPM	750 cP
Glass Transition (Tg)	TMA	215 °C
Coefficient of Thermal Expansion (CTE, α_1)	TMA	53 ppm
Moisture Absorption (% wt. gain)	24 hr. immersion @ 23°C	0.4 %
Tensile Strength @ 25°C	ASTM D 638-02a	77 MPa
Modulus @ 25°C	DMA	1.3 GPa
Dielectric Constant (Dk)	Cavity Perturbation Method @ 20GHz	2.6
Dissipation Factor (Df)		0.0042
Td (5%)	TGA	450 °C
Flammability	UL94	V-0
Recommended Storage Temp		Room Temperature

Data is for reference only and may vary depending on testing method used.

RECOMMENDED FORMULATION & USE:

DMI-7005 is recommended for use as a polyimide (PI) replacement resin in FCCL and CCL applications. The material has excellent green strength in film form prior to curing. The material may be homocured (no catalyst) at higher temperatures to increase the Tg. Generally 1 hour at 200°C is sufficient to fully cure a completely dry film.

Film formation should include a drying step sufficient to remove all of the anisole solvent in the mixture. Depending upon film thickness 110 – 115°C for one or more hours is generally required.

CONTACT:

REQUEST A SAMPLE OR PLACE AN ORDER

Customer Support

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REF: DMI Part Number: R1373